

In the Abstract:

Please amend the Abstract as follows:

--~~The invention relates to a A housing can be used~~ for high-power components, especially high-power capacitors. ~~The invention is based on the idea of providing a A housing, which has a carrier platform made from a suitable electrically insulating material and a preferably metallic cover, wherein the thermal expansion coefficients of the platform and of the cover are matched to each other. This matching is achieved according to the invention by adjusting the glass-fiber coefficient of a fiber-composite material.~~--